

Surface Mount Solutions

Attenuators Resistors Terminations



Surface Mount Solutions

SERIES ANT, ANR

RESISTORS & TERMINATIONS



High Power, Aluminum Nitride, Thin Film, Drop-in - 10-600 Watts, DC-4 GHz

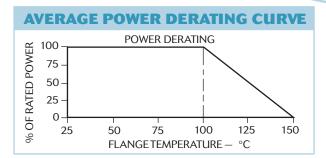
GENERAL INFORMATION

These high power devices are designed to dissipate power in RF circuits when mounted to an appropriate heat sink. The terminations provide a low VSWR under maximum power conditions. The resistor configurations are typically used in "Wilkinson" type power divider networks, or to terminate 3 dB stripline or microstrip hybrids. Aluminum nitride is used for those applications where the use and disposal of beryllium oxide is a concern.

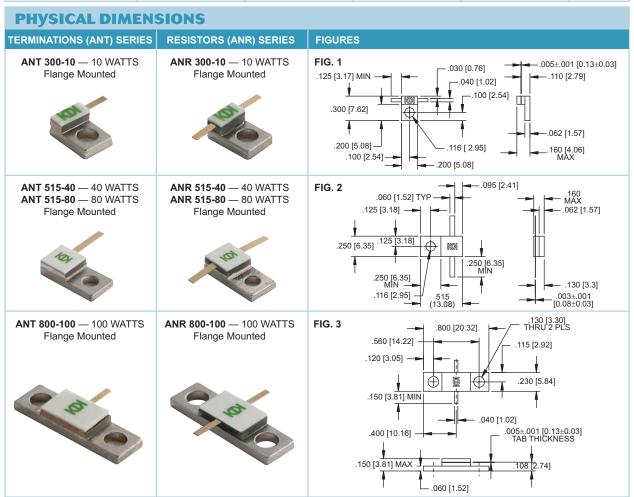
- 1. Input power ratings are based on flange temperature of 100° C maximum.
- 2. 50 and 100 Ohms standard. Other values from 10-500 Ohms available on special order. Contact factory for details. Standard tolerance ±5%. Specify resistance value when ordering.
- 3. VSWR applies to termination style only



| GENERAL | SPECIFICATIONS |
|-------------------|--|
| Resistive Element | Thin Film |
| Substrate | Aluminum Nitride |
| Cover | Alumina Ceramic |
| Mounting Flange | Copper, Nickel Plated per QQ-N-290 |
| Tab | Beryllium Copper, Gold Plated per MIL-G-4520 4 |

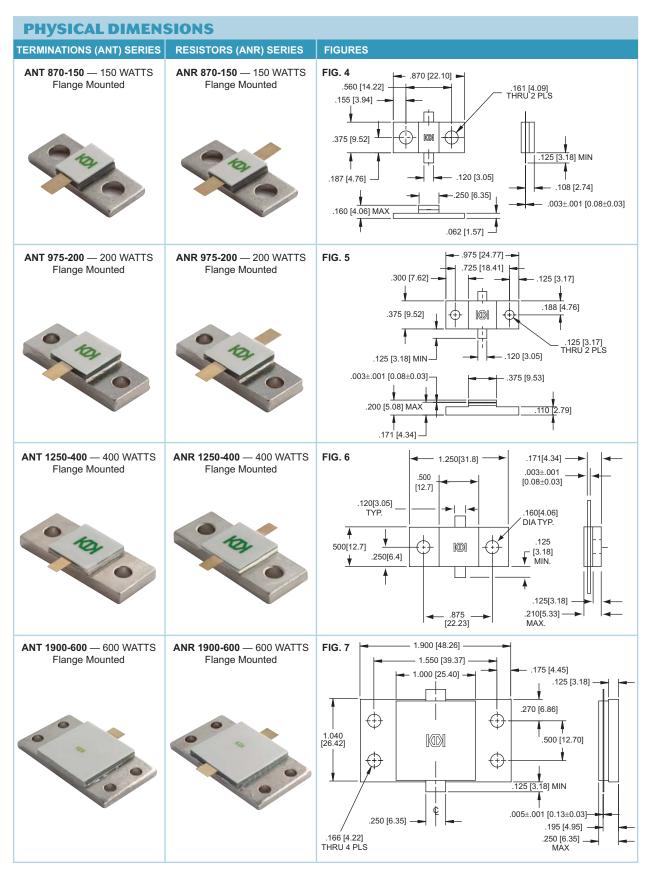


| PERFORMANCI | PERFORMANCE SPECIFICATIONS | | | | | | | | | | | | |
|--------------------|----------------------------|-----------------------------|----------------------------|----------------------------|---------------|--|--|--|--|--|--|--|--|
| Model | Frequency Range | Input Power (Watts Avg.) | VSWR (Typical) (Note 3) | Capacitance (pF) (Typ.) | Figure No. | | | | | | | | |
| ANT & ANR 300-10 | DC-4.0 GHz | 10 | 1.25:1 | 1.0 | 1 | | | | | | | | |
| ANT & ANR 515-40 | DC-2.5 GHz | 40 | 1.15:1 | 1.0 | 2 | | | | | | | | |
| ANT & ANR 515-80 | DC-1.0 GHz | 80 | 1.25:1 | 1.6 | 2 | | | | | | | | |
| ANT & ANR 800-100 | DC-2.0 GHz | 100 | 1.25:1 | 1.4 | 3 | | | | | | | | |
| ANT & ANR 870-150 | DC-2.0 GHz | 150 | 1.25:1 | 4.5 | 4 | | | | | | | | |
| ANT & ANR 975-200 | DC-1.0 GHz | 200 | 1.25:1 | 4.5 | 5 | | | | | | | | |
| ANT & ANR 1250-400 | DC-500 MHz | 400 | 1.50:1 | 7.0 | 6 | | | | | | | | |
| ANT & ANR 1900-600 | DC-500 MHz | 600 | 1.50:1 | 15.0 | 7 | | | | | | | | |



SERIES ANT, ANR

RESISTORS & TERMINATIONS





A3RS91.1

High Power Chip Termination 100 Watts



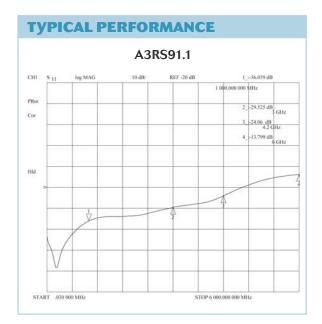


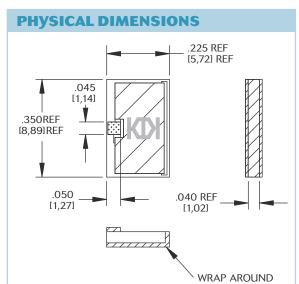
When properly mounted on an appropriate heat sink, this chip device provides high power dissipation capabilities. Ideal for ferrite isolator applications, the improved thin film design technology and laser trimming provide proven RF power capabilities to meet the demands of today's CDMA and WCDMA system requirements. Aluminum Nitride is featured for those applications where the use and disposal of Beryllium oxide is a concern.

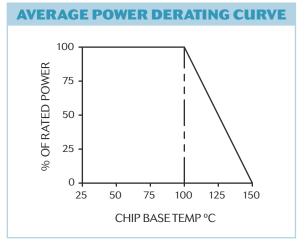
- · Environmentally friendly AIN substrate
- · High performance, thin film element
- Power 100 Watts
- New adhesion process results in improved terminal strength
- On-chip matching network improves frequency performance over the DC-3 GHz frequency range

| SPECIFICATIONS | |
|-----------------------|------------------|
| Parameters | Specifications |
| Frequency Range | DC to 3 GHz |
| Power | 100 Watts* |
| VSWR | 1.10:1 max |
| Resistance | 50 Ohms +/- 5% |
| Operating Temperature | -55 °C to 150 °C |
| Substrate | Aluminum Nitride |

^{*} Refer to average power derating curve chart.









SERIES ANC

RESISTORS, TERMINATIONS

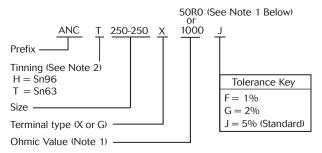
High Power Chip, Aluminum Nitride - 50 & 100 Ohms

GENERAL INFORMATION

When mounted on an appropriate heat sink, these chip devices provide high power dissipation in terminations and as balancing resistors in Wilkinson power divider networks. Laser trimming provides maximum RF power capability. Aluminum nitride is used for those applications where the use and disposal of beryllium oxide is a concern.

ORDERING INFORMATION

EXAMPLE: Typical Model No.



NOTES

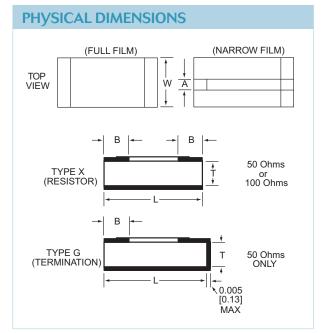
1. Resistance value is expressed using military 4-digit call-out. 50R0 = 50 Ohms 1000 = 100 Ohms

Other values from 10–500 Ohms may be available as special order. Contact factory for availability.

Tinning with Sn96 "Lead Free" high temperature solder will maintain RoHS compliance.

| GENERAL SPEC | CIFICATIONS |
|----------------------|----------------------------------|
| Solderable Terminals | Electroplated Silver over Nickel |
| Substrate | Aluminum Nitride |
| Resistive Element | Thin Film |





| PERFORMA | PERFORMANCE SPECIFICATIONS | | | | | | | | | | | | | |
|----------------|-------------------------------------|--------|---------|-----------------|-------|--------------|-------|--------|--------------------------------|--------------------------------|-------------|--------------|-----|--------|
| Model Prefix | W L Model Prefix in [mm] in [mm] in | | T in | T in [mm] ir | | A in [mm] | | [mm] | Capacitance (pF) Typical | Termination VSWR Typical | Power CW | FREQ. GHz | | |
| ANC 50-50 | 0.050 | [1,27] | 0.050 | [1,27] | 0.010 | [0,25] | N/A | | 0.010 | [0,25] | 0.5 | 1.25 | 5 | DC-4.0 |
| ANC 50-100 | 0.050 | [1,27] | 0.100 | [2,5] | 0.010 | [0,25] | N/A | | 0.020 | [0,51] | 1.0 | 1.25 | 10 | DC-2.0 |
| ANC 100-200 | 0.100 | [2,5] | 0.200 | [5,1] | 0.040 | [1,02] | N/A | | 0.030 | [0,76] | 1.0 | 1.25 | 10 | DC-4.0 |
| ANC 200-200 | 0.200 | [5,1] | 0.200 | [5,1] | 0.040 | [1,02] | 0.085 | [2,2] | 0.040 | [1,02] | 1.2 | 1.25 | 30 | DC-4.0 |
| ANC 250-250-40 | 0.250 | [6,4] | 0.250 | [6,4] | 0.040 | [1,02] | 0.085 | [2,2] | 0.050 | [1,27] | 1.0 | 1.15 | 40 | DC-2.5 |
| ANC 250-250-80 | 0.250 | [6,4] | 0.250 | [6,4] | 0.040 | [1,02] | N/A | | 0.050 | [1,27] | 1.6 | 1.25 | 80 | DC-1.0 |
| ANC 250-375 | 0.250 | [6,4] | 0.375 | [9,5] | 0.040 | [1,02] | N/A | | 0.050 | [1,27] | 4.5 | 1.25 | 125 | DC-1.0 |
| ANC 350-225 | 0.350 | [8,9] | 0.225 | [5,7] | 0.040 | [1,02] | 0.045 | [1,14] | 0.050 | [1,27] | 1.4 | 1.25 | 100 | DC-2.0 |
| ANC 375-375 | 0.375 | [9,5] | 0.375 | [9,5] | 0.040 | [1,02] | 0.250 | [6,4] | 0.050 | [1,27] | 4.5 | 1.25 | 200 | DC-1.0 |



SERIES KAC

Surface Mount Terminations (SMT)

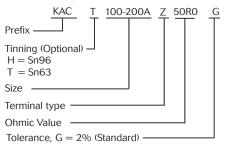
High Power, Aluminum Nitride (AIN), 10 - 150 Watts

GENERAL INFORMATION

Aeroflex/Inmet's series of High PowerSurface MountTerminations are ideal for high frequency applications where small size and low costs are an important design criteria. The ability of these chips to be directly mounted to the PC Board eliminates the need for expensive mounting flanges and input tabs. Large solderable surface areas on the bottom of the chips allows for higher power dissipation in smaller sizes. All KAC series chips are manufactured using environmentally friendly Aluminum Nitride ceramic and are classified as RoHS compliant.

ORDERING INFORMATION





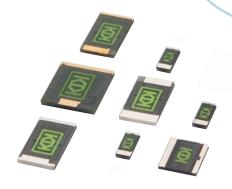
NOTE

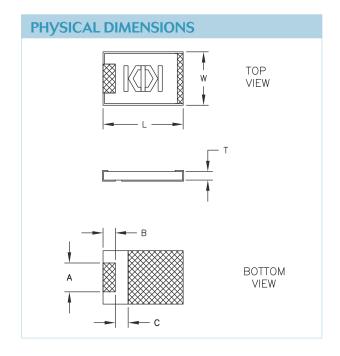
Tinning with Sn96 "Lead Free" high temperature solder will maintain RoHS compliance.

| GENERAL SPECIFICATIONS | | | | | | | | |
|------------------------|----------------------------------|--|--|--|--|--|--|--|
| Substrate | Aluminum Nitride | | | | | | | |
| Solderable Terminals | Electroplated Silver over Nickel | | | | | | | |
| Resistive Element | Proprietary Thick Film | | | | | | | |
| Operating Temperature | -55 to +150°C | | | | | | | |
| Impedance (Nominal) | 50 Ohms | | | | | | | |









| PERFORMA | NCE | SPEC | CIFICA | ATIO | NS | | | | | | | | | | |
|----------------|-------|--------|--------|--------|-------|-----------|-------|--------|-------|--------|-------|--------|------|-------------|------------------|
| Model Prefix | in W | (mm) | In | (mm) | in | Γ (mm) | in | (mm) | in E | (mm) | in (| (mm) | VSWR | Power CW | Frequency GHz |
| KAC 60 - 120A | 0.060 | (1,52) | 0.120 | (3,05) | 0.025 | (0,64) | 0.054 | (1,37) | 0.026 | (0,66) | 0.013 | (0,33) | 1.25 | 10 | DC - 4.0 |
| KAC 100 – 200A | 0.100 | (2,5) | 0.200 | (5,1) | 0.040 | (1,02) | 0.050 | (1.27) | 0.025 | (0,64) | 0.035 | (0,89) | 1.25 | 20 | DC - 2.5 |
| KAC 250 – 250A | 0.250 | (6,4) | 0.250 | (6,4) | 0.040 | (1,02) | 0.040 | (1,02) | 0.043 | (1,09) | 0.020 | (0,51) | 1.25 | 75 | DC - 4.0 |
| KAC 250 – 375A | 0.250 | (6,4) | 0.375 | (9,5) | 0.040 | (1,02) | 0.135 | (3,43) | 0.058 | (1,47) | 0.060 | (1,52) | 1.25 | 100 | DC - 3.0 |
| KAC 375 – 375A | 0.375 | (9,5) | 0.375 | (9,5) | 0.040 | (1,02) | 0.125 | (3,18) | 0.057 | (1,48) | 0.030 | (0,76) | 1.25 | 150 | DC - 3.0 |



SERIES PCX

HIGH POWER COAXIAL TERMINATIONS

DC to 6 GHz

GENERAL INFORMATION

The PCX Series High Power Terminations are designed to dissipate RF power when mounted to a heat sink or chill plate. Power levels up to 500 watts in 50 ohm impedance are available in units with SMA or Type N, male or female connectors. High stability thin film resistive elements on beryllium oxide substrates are used to insure stable VSWR performance over temperature and environmental conditions.

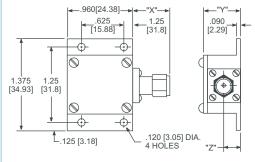
NOTES

- 1. Input power ratings based on case temperature of 85°C maximum.
- 2. Connectors: SMA Stainless Steel Passivated per MIL-C-39012, Type N - Nickel Plated Brass per MIL-C-39012
- 3. Housing: Copper, Nickel Plated per QQ-N-290



| PERFORMANCE SPECIFICATIONS | | | | | | | | | | | | | |
|--|---------------------------------|--------------------|--|--|---------|--|--|--|--|--|--|--|--|
| Part Number | Input Power (Watts) (Note 1) | Frequency Range | Connector Type (Note 2) | VSWR (Typical) | Outline | | | | | | | | |
| PCX050-F-50 PCX050-M-50 | 50 | DC - 6 GHz | SMA Female SMA Male | DC-3 GHz: 1.25:1 3 - 6 GHz: 1.35:1 | А | | | | | | | | |
| PCX050-F-100 PCX050-M-100 | 100 | DC - 3 GHz | SMA Female SMA Male | DC- 3 GHz: 1.25:1 | А | | | | | | | | |
| PCX050-F-150 PCX050-M-150 PCX100-F-150 PCX100-M-150 | 150 | DC - 2 GHz | SMA Female SMA Male N Female N Male | DC - 1 GHz: 1.15:1 1 - 2 GHz: 1.40:1 | В | | | | | | | | |
| PCX050-F-250 PCX050-M-250 PCX100-F-250 PCX100-M-250 | 250 | DC -800 MHz | SMA Female SMA Male N Female N Male | DC - 200 MHz: 1.15:1 200 - 400 MHz: 1.40:1 400-800 MHz: 1.30:1 | В | | | | | | | | |
| PCX100-M-500 | 500 | DC - 200 MHz | N Male | DC - 200 MHz: 1.15:1 | В | | | | | | | | |

PHYSICAL DIMENSIONS

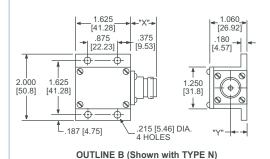


| MODEL | "X" | "У" | "Z" |
|--------------|---------|---------|--------|
| PCX050-F-50 | .375 | .560 | .260 |
| | [9.53] | [14.22] | [6.60] |
| PCX050-M-50 | .507 | .560 | .260 |
| | [12.88] | [14.22] | [6.60] |
| PCX050-F-100 | .375 | .560 | .260 |
| | [9.53] | [14.22] | [6.60] |
| PCX050-M-100 | .507 | .560 | .260 |
| | [12.88] | [14.22] | [6.60] |



SMA 50 & 100 WATTS

OUTLINE A (Shown with SMA)



| MODEL "X | ." | "У" | |
|---------------------------------|---------------|------|------|
| PCX050-F-150, 250 [9.53] | [13.08] | .375 | .515 |
| PCX050-M-150, 250 [9.53] | [13.08] | .375 | .515 |
| PCX100-F-150, 250, 5 [18.69] | 00 [12.9] | .736 | .508 |
| PCX100-M-150, 250, 5 | 500 [12.9] | .819 | .508 |



SMA OR N CONNECTORS 150, 250 & 500 WATTS



SERIES PPC, NPC

RESISTORS, TERMINATIONS

High Power Chip - 50 & 100 Ohms

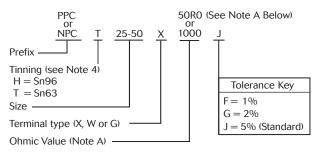
RoHS Compliant

GENERAL INFORMATION

When mounted on an appropriate heat sink, these chip devices provide high power dissipation in terminations and as balancing resistors in Wilkinson power divider networks. Laser trimming provides maximum peak and average RF power capability.

ORDERING INFORMATION

EXAMPLE: Typical Model No.



NOTE A

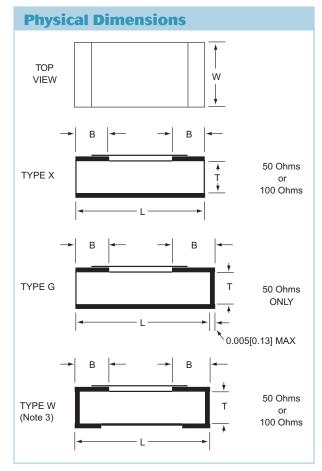
Resistance value is expressed using military 4-digit call-out. 50R0 = 50 Ohms 1000 = 100 Ohms

Other values from 10–500 Ohms may be available as special order. Contact factory for availability.

| GENERAL SPI | ECIFICATIONS |
|----------------------|---|
| Solderable Terminals | Electroplated Silver over Nickel (PPC) Gold over Nickel alloy (NPC) |
| Substrate | Beryllium Oxide Ceramic |
| Resistive Element | Thin Film and Thick Film* |

- 1. The "L" and "T" dimensions are for the substrate only and do not include terminal thickness or optional tinnina thickness.
- 2. Thermal Resistance (R°) is measured in °C/W between resistive film and mounting surface.
- 3. The CW power rating is based on maximum film temperature of +150°C and with maximum heatsink temperature of +100°C. Power is based on infinite and ideal heatsink. Type "W" termination style does not have full back plane metallization and typically handles 1/10 the rated power.
- Tinnning with Sn96 "Lead Free" high temperature solder will maintain RoHS compliance.





| PERFORM | PERFORMANCE SPECIFICATIONS | | | | | | | | | | | | | |
|-----------------|----------------------------|-----------|-------|-------------------|------------|--------------------|-------|-----------|-----------------------------|----------------------------|--------------|-------------------|--|--|
| Model Prefix | in | / [mm] | (Not | - e 1) [mm] | (Not in | T te 1) [mm] | in | B [mm] | Capacitance (pF) Typical | Rذ C/W Max. (Note 2) | C/W Power | Freq. GHz (**) | | |
| *PPC 100-200A | 0.100 | [2,5] | 0.200 | [5,1] | 0.040 | [1,02] | 0.030 | [0,76] | 0.8 | 0.80 | 20W | DC-4.0 | | |
| *PPC 250-250A | 0.250 | [6,4] | 0.250 | [6,4] | 0.040 | [1,02] | 0.050 | [1,27] | 1.2 | 0.30 | 40W | DC-2.5 | | |
| *PPC 250-375A | 0.250 | [6,4] | 0.375 | [9,53] | 0.040 | [1,02] | 0.050 | [1,27] | 3.5 | 0.15 | 150W | DC-1.0 | | |
| NPC 25-50 | 0.025 | [0,64] | 0.050 | [1,27] | 0.010 | [0,25] | 0.012 | [0,305] | 0.3 | 3.90 | 3W | DC-12.4 | | |
| *NPC 50-50 | 0.050 | [1,27] | 0.050 | [1,27] | 0.010 | [0,25] | 0.012 | [0,305] | 0.5 | 1.90 | 5W | DC-10 | | |
| *NPC 50-100 | 0.050 | [1,27] | 0.100 | [2,5] | 0.010 | [0,25] | 0.017 | [0,43] | 1.0 | 0.72 | 10W | DC-4.0 | | |
| NPC 75-150 | 0.075 | [1,91] | 0.150 | [3,8] | 0.010 | [0,25] | 0.020 | [0,51] | 1.8 | 0.29 | 15W | DC-4.0 | | |

^{*} Low cost thick film models available on these sizes. Consult factory for specifications.

^{**} Typical VSWR for all terminations is 1.25:1

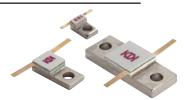


SERIES PPA

ATTENUATORS

High Power - DC-4 GHz

RoHS Compliant





The Aeroflex/Inmet PPA Series of attenuators utilize a Beryllium Oxide chip and thin film technology to provide devices which can dissipate up to 100 Watts of RF power. The PPA series must be thermally bonded to a heat sink, using the mounting holes provided, in order to operate within the temperature rating indicated. The flange temperatures must not exceed 100°C under rated power conditions.

ORDERING INFORMATION

The Power Attenuators listed are available in 1 dB increments from 1 thru 20 dB. Specify by selecting any of the series listed and add the attenuation value desired to the basic series designation. (See Note 3)

EXAMPLE:



| GENERAL SPECIFICATIONS | | | | |
|------------------------|---|--|--|--|
| Impedance | 50 Ohms | | | |
| Operating Temp. | −55 °C to +150°C | | | |
| Attenuation Stability | 0.0001 dB/dB/°C | | | |
| Substrate | Beryllium Oxide Ceramic | | | |
| Resistive Element | Proprietary Thin Film | | | |
| Flange | Copper, Nickel Plated per QQ-N-290 | | | |
| Tabs | Beryllium Copper, Gold Plated per MIL-G-45204 | | | |
| Cover | Alumina Ceramic | | | |

| PERFORMANCE SPECIFICATIONS | | | | | | | | |
|---------------------------------|---|-----------------------------------|---------------------------|------|----------------------------------|------------------------------|------------------------------|---|
| Model | Attenuation ⁽¹⁾ 1 dB Increments (dB) | Frequency ⁽¹⁾ Range | Input Power (Watts) | dB | Attenuation / (dl DC-1 GHz | | 2.5-4 GHz | VSWR (Typical) ² |
| PPA 10 11-20 | 1-20 | DC-4 GHz | 10 | 1-10 | ±0.5 ±1.0 | ±0.5 ±2.0 | ±1.0 ±3.0 | 1.3:1 |
| PPA 20 6-9 10-15 16-20 | 1-20 | DC-4 GHz | 20 | 1-5 | ±0.5 ±0.5 ±0.75 ±1.0 | ±0.5 ±0.5 ±1.0 ±2.0 | ±0.5 ±1.0 ±1.5 ±3.0 | 1.15:1 – DC-1.0 GHz 1.35:1 – 1.0-2.5 GHz 1.50:1 – 2.5-4.0 GHz |
| PPA 50 | 1-20 | DC-1 GHz | 50 | | ±0.3 DC-5 ±0.5 500 <i>l</i> | | | 1.25:1 – DC-500 MHz 1.50:1 – 500 MHz–1 GHz |
| PPA 100 | 1-20 | DC-500 MHz | 100 | | ±0.5 | | | 1.25:1 – DC-200 MHz 1.50:1 – 200-500 MHz |

PHYSICAL DIMENSIONS .040 [1.02] x .005±.001 THK [0.13±0.03] .003±.001 [0.08±0.03] .375 [9.52] NOTES .060 [1.52] TYP 1. Custom products .171 [4.34] .116 [2.95] DIA. .175 [4.45] are available .160 [4.06] MAX. at higher .125 [3.18] MIN. .125 [3.18] frequencies THRU 2 PLS with optimized VSWR and .300 [7.62] ф .375 [9.53] attenuation accuracy over .100 [2.54] narrow frequency .100 [2.54] .250 [6.35] MIN TYP _ .200 [5.08] .062 [1.58] .725 [18.42] 2. VSWR as measured .110 [2.79] .125 [3.18] in a 0.125" ground .105 [2.67] .200 [5.08] MAX ■ .975 [24.77] plane stripline circuit. **PPA10 OUTLINE PPA50 OUTLINE** 3. Standard values 1, 2, 3, 4, 5, 6, 10, 20 dB. .003±.001 [0.08±0.03] 1.250 [31.75] Non-std values available .060 [1.52] x 003±.001 THK [0.08±0.03] .875 [22.23] as special order. .171 [4.34] .405 [10.29] .150 [3.81] MAX. .188 [4.76] .250 [6.35] MIN. .116 [2.95] DIA. KODXI .515 [13.08] .250 [6.35] .500 [12.70] \oplus .250 [6.35] .250 [6.35] MIN TYP .125 [3.18] .125 [3.18] -.250 [6.35] .060 [1.52] TYP -.125 [3.18] .500 [12.70] .210 [5.33] MAX .105 [2.67] **PPA20 OUTLINE PPA100 OUTLINE**



KEY: Inches [Millimeters] .XX ±.03 .XXX ±.010 [.X ±0.8 .XX ±0.25]

SERIES PCA, PCAA

ATTENUATORS, CHIP

Low Power - DC-18 GHz

FEATURES

- Laser Trimmed
- · Temperature Stable

GENERAL INFORMATION

The PCA and PCAA Series consists of a laser trimmed distributed thin film element on an alumina ceramic substrate with solderable terminals. Two sizes are available. The PCA size operates to 12.4 GHz and the PCAA size operates to 18.0 GHz. Both sizes are available with leads and wrap around conductors for ease of installation. The PCAF and PCAAF options are designed for "flip-chip" application in lower frequency circuits.

PCA & PCAA SERIES DATA

- · Substrate: 96% Alumina
- · Solderable Terminals: Electroplated Silver over Nickel
- · Resistive Element: Proprietary Thin Film
- · Wrap around Ground Terminal available, "W" option
- Wrap around-all terminals—"F" option
- Standard values 1, 2, 3, 4, 5, 6, 10, 20 dB
- · Non-std. values available as special order

ORDERING INFORMATION

The attenuators listed are available in 1 dB increments from 1 through 20 dB. When ordering, to specify the correct part number for the desired attenuation value, select any of the series listed and add the attenuation value desired to the basic series designation.

Options (Note 4)

L = Lead/Tab (Gold Plated BeCu)

W = Wrap around ground only

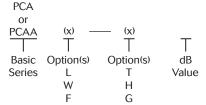
F = Wrap around all terminals (flip-chip)

 $T\!=\!$ Tinned terminals (any terminal type) Sn63

H = Tinned terminals (any terminal type) Sn96

G = Gold plated terminals

EXAMPLE:

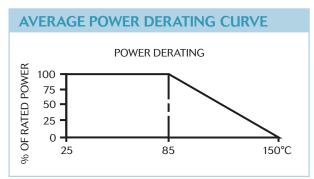


EXAMPLES: PCAW-T3 PCAAF-G3





| GENERAL SPECIFICATIONS | | |
|------------------------|-----------------|--|
| Impedance | 50 Ohms | |
| Operating Temperature | −55°C to +150°C | |
| Attenuation Stability | 0.0001 dB/dB/°C | |



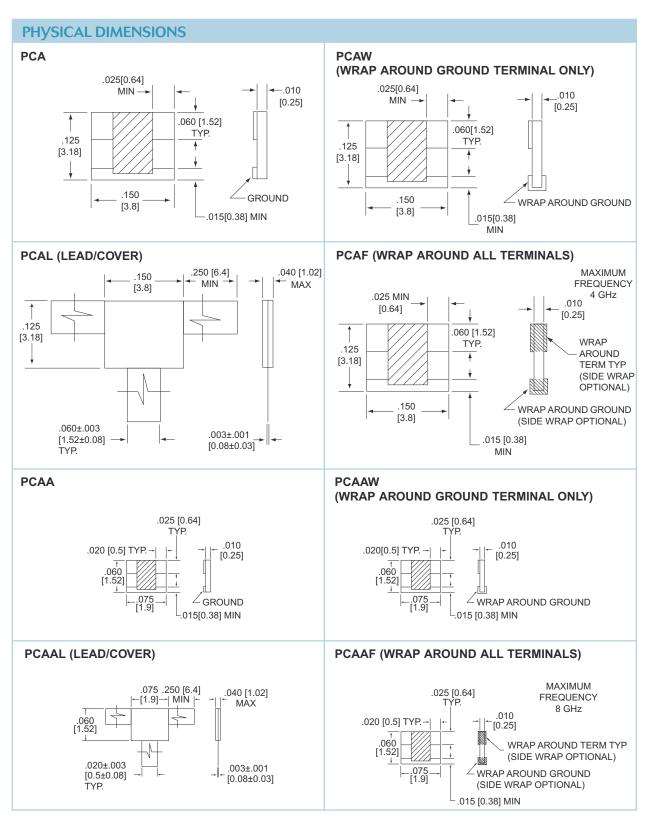
- 1. Performance of other dB values vary dependent on attenuation. Contact factory for specifications for fractional dB values.
- 2. Performance is based on device mounted in matched 50 Ohm line.
- 3. Rated power 1.5 Watts input PCA, 100 mw PCAA.
- Tinning with Sn96 "Lead Free" high temperature solder will maintain RoHS compliance.

| PERFORM | PERFORMANCE SPECIFICATIONS | | | | | | | |
|------------------------------|-----------------------------------|---|---|--------------------------------------|-----------------------------------|---|---|--------------------------------------|
| Increments (dB) Note 1 | DC - 4 GHz PCA, PCAA Series | Attenuation Acc 4 - 8 GHz PCA, PCAA Series | curacy (dB) Note 2 8 - 12.4 GHz PCA, PCAA Series | 12.4 - 18 GHz PCAA Series Only | DC - 4 GHz PCA, PCAA Series | VSWR (Typ 4 - 8 GHz PCA, PCAA Series | ical) Note 2 8 - 12.4 GHz PCA, PCAA Series | 12.4 - 18 GHz PCAA Series Only |
| 1 - 3 | ± 0.5 | ± 0.5 | ± 0.5 | ± 0.5 | 1.25 | 1.35 | 1.50 | 1.50 |
| 4 - 6 | ± 0.5 | ± 0.5 | ± 0.5 | ± 0.75 | 1.25 | 1.35 | 1.50 | 1.50 |
| 7 - 10 | ± 0.5 | ± 0.5 | ± 0.75 | ± 1.0 | 1.25 | 1.35 | 1.50 | 1.50 |
| 11 - 15 | ±0.75 | +0.5 -3.0 | +0.5 -4.0 | _ | 1.25 | 1.35 | 1.50 | _ |
| 16 - 20 | ± 1.0 | +0.5 -4.0 | _ | _ | 1.25 | 1.35 | _ | _ |

SERIES PCA, PCAA

ATTENUATORS, CHIP

Low Power - DC-18 GHz





RESISTORS & TERMINATIONS

High Power, Thin Film, Drop-in - 10-650 Watts, DC-4 GHz

GENERAL INFORMATION

These high power devices are designed to dissipate power in RFcircuits when mounted to an appropriate heat sink. The terminations provide a low VSWR under maximum power conditions. The resistor configurations are typically used in "Wilkinson" type power divider networks, or to terminate 3 dB stripline or microstrip hybrids.

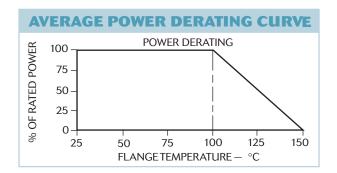
RoHS Compliant



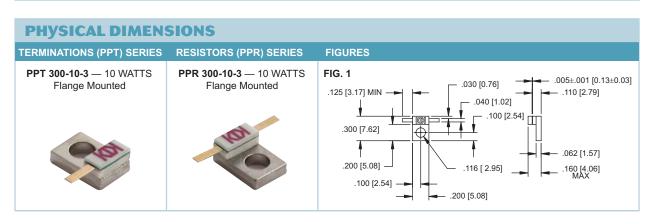
- 1. Input power ratings are based on flange temperature of 100° C maximum.
- 50 and 100 Ohms standard. Other values from 10-500 Ohms available on special order. Contact factory for details. Standard tolerance ±5%. Specify resistance value when ordering.
- 3. VSWR applies to termination style only.

| GENERAL SPECIFICATIONS | | | | |
|------------------------|--|--|--|--|
| Resistive Element | Thin Film and Thick Film* | | | |
| Substrate | Beryllium Oxide Ceramic | | | |
| Cover | Alumina Ceramic | | | |
| Mounting Flange | Copper,Nickel Plated per QQ-N-290 | | | |
| Tab | Beryllium Copper,Gold Plated per MIL-G-45204 | | | |

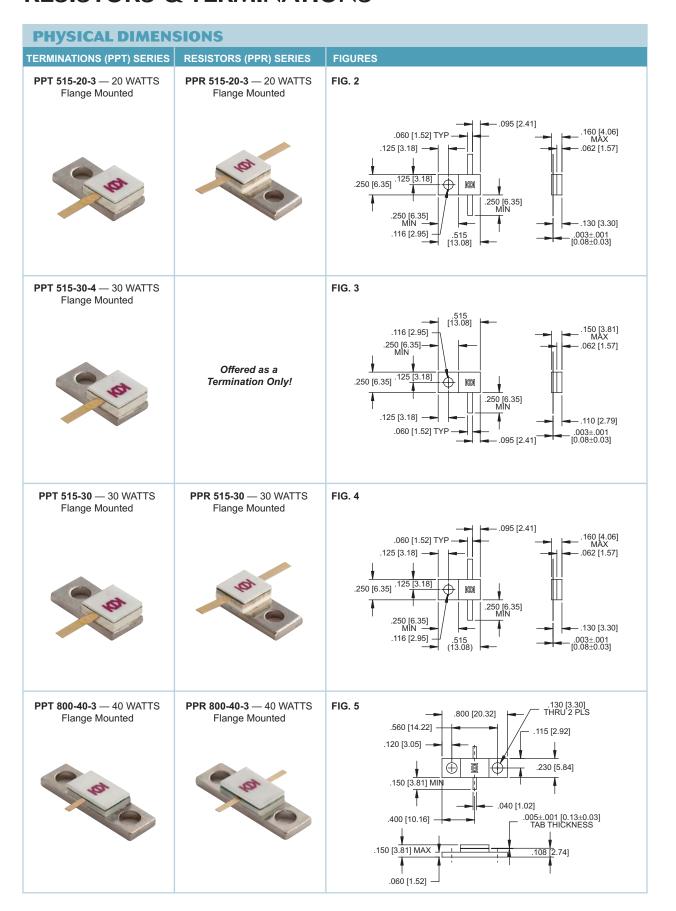
^{*} Low cost thick film models available on some sizes. Consult Factory for specifications.



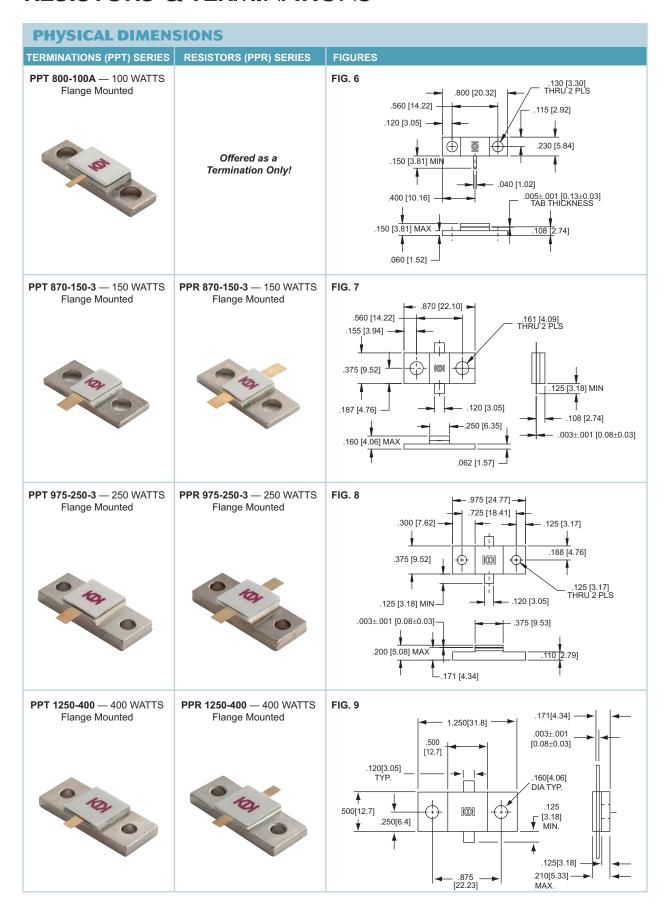
| Model | Frequency Range | Input Power (Watts Avg.) | VSWR (Typical) (Note 3) | Capacitance (pF) (Typ.) | Figure No. |
|----------------------|--------------------|-----------------------------|--|----------------------------|---------------|
| PPR & PPT 300-10-3* | DC-4.0 GHz | 10 | 1.35:1 —DC-4.0 GHz | 0.8 | 1 |
| PPR & PPT 515-20-3* | DC-2.0 GHz | 20 | 1.10:1 –DC-1.0 GHz 1.25:1 –1.0-2.0 GHz | 0.8 | 2 |
| PPT 515-30-4 | DC-4.0 GHz | 30 | 1.20:1 -DC-40 GHz | 1.2 | 3 |
| PPR & PPT 515-30* | DC-2.0 GHz | 30 | 1.10:1 –DC-1.0 GHz 1.25:1 –1.0-2.0 GHz | 0.8 | 4 |
| PPR & PPT 800-40-3 | DC-4.0 GHz | 40 | 1.25:1 -DC-4.0 GHz | 1.4 | 5 |
| PPT 800-100A | DC-2.0 GHz | 100 | 1.25:1 -DC-2.0 GHz | 1.4 | 6 |
| PPR & PPT 870-150-3* | DC-1.0 GHz | 150 | 1.20:1 —DC-500 MHz 1.35:1 —500-1000 MHz | 3.5 | 7 |
| PPR & PPT 975-250-3 | DC-1.0 GHz | 250 | 1.25:1 —DC-500 MHz 1.35:1 —500-1000 MHz | 5.0 | 8 |
| PPR & PPT 1250-400 | DC-500 MHz | 400 | 1.50:1 -DC-500 MHz | 7.0 | 9 |
| PPR &PPT 1900-800 | DC-500 MHz | 650 | 1.25:1 —DC-200 MHz 1.50:1 —200-500 MHz | 10.2 | 10 |



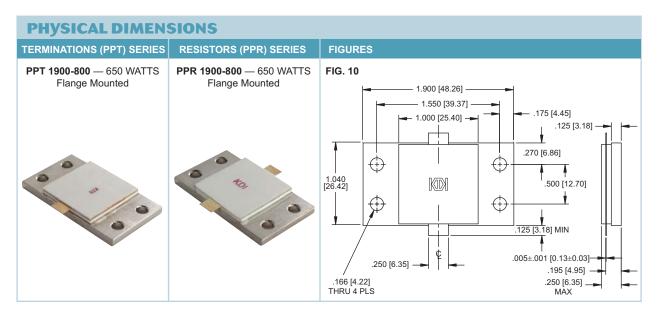
RESISTORS & TERMINATIONS



RESISTORS & TERMINATIONS



RESISTORS & TERMINATIONS







Mounting Application Notes

Mounting of High Power Flange Devices

When mounting High Power Flange Devices in a circuit, there are several key issues that should be taken into account.

Heat Sink Design

The heat sink the device is mounted to must be designed to maintain the temperature (design) while it is dissipating the power (heat) given it by the device. (The derating specifications are given in the applicable data sheets.)

Flatness of mating surfaces

Flatness of the heat sink and of the mounting area of the device (flange) should be 0.001" maximum. The idea is to have the best possible contact between the heat sink and the device.

Thermal Compound

To fill any microscopic voids or air gaps the use of thermal compound is recommended to a thickness of 0.002" maximum.

Stress Relief on Tab

Although it is not always possible in High Frequency applications a small loop for stress relief on the solder tab is recommended. This reduces any mechanical stress on the joints.

Apply a small amount of thermal compound to the mounting area of the flange of the device. Spread it completely on the flange using a razor blade or other smooth tool. When seating the device, align the tab/tabs over the corresponding area on the circuit board. Screw down the device using the recommended torque for the appropriate screw size in the table below. Aeroflex / Inmet recommends the use of a lock washer and a flat washer in the installation. See Figure 1

| Thread Size | Torque Setting |
|-------------|----------------|
| 2-56 | 4 inch-pounds |
| 4-40 | 6 inch pounds |
| 6-32 | 8 inch pounds |
| 8-32 | 12 inch pounds |
| 10-32 | 18 inch pounds |

Solder the tab/tabs using SN63 (179° C eutectic) solder and a small amount of RMA flux. After all the solder is complete all of the flux must now be removed using a cleaning agent.

Mounting of Chip Devices

This application note covers the recommended mounting techniques for the proper conduction cooling and RF performance of a surface mounted (flangeless) chip attenuator, termination or resistor.

Initial Considerations

There are two primary considerations for a surface mounted power device; Power Dissipation and RF Performance. In order to remove the dissipated power from this type chip they must be provided with adequate conductive cooling. This will prevent excessive chip temperatures leading to damage and early failure of the device. RF performance is also dependent on proper mounting. Since these devices are being mounted to a circuit board, inductance to ground is introduced by the vias to the ground plane. To reduce this effect and lower the thermal resistance between the component and ground plane, the following items are recommended:

- 1. Maximize the use of thermally conductive vias around and under the device.
- 2. Use of heavy copper cladding (2 oz.) on the circuit board as a heat spreader.

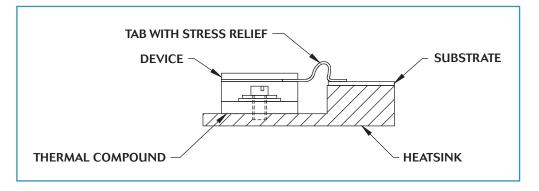
Solders

Aeroflex / Inmet recommends the use of the solders in the chart below when installing a surface mount chip. Also listed are recommended platings for the heatsink/baseplate that a device might be mounted to instead of a circuit board.

Mounting

The first step when mounting a chip device to the circuit board is to determine the proper size and location of the solder pads. Aeroflex / Inmet recommends providing pads that are 0.010" to 0.020" over the device's termination size and are centered on the axis of the chip. This allows for self-centering of the chip and a proper solder fillet formation. Skewing and "tombstoning" can occur if this is not followed. See Figure 2

Figure 1: High Power Flange Device Mounting





Preparation

- Before any solder attachment, parts and circuit boards must be free of any oils or dirt. Isopropyl alcohol can be used for this task.
- 2. Apply a small amount of RMA flux (MIL-F-14256) to the areas to be soldered.
- 3. SN63 solder is generally recommended for use. This may be a preform, solder paste or wire. If preforms are used, select a size that is 0.005"to 0.010" larger than the size of the pad.
- 4. When soldering is complete the circuit board must be cleaned to remove any flux residue. This can be done in an ultrasonic cleaner or vapor degreaser. Flux manufacturers have recommended solvents or cleaning solutions for their products.

Pretinning

Pretinning can be done with either a solder pot or by depositing and reflowing solder on the device. (Aeroflex-Inmet can supply pretinned devices, SN63 or SN96).

Tabs

When attaching tabs to a device we recommend using SN96 (221° C) to attach the tab to the chip. Then, solder the tab to the circuit board using SN63 (183° C).

Wire Bonding

Attach the device to the circuit board using solder as described above. Clean and remove any flux residues. Ultrasonically bond wire or ribbon to gold termination pads using a wedge or ball bonder. NOTE: Gold plated chips are required for this method.

Tuning

Maximum VSWR, as specified on the data sheet, can be achieved without additional tuning. Lower VSWR can be achieved with stub or lumped element tuning. However, this can result in a narrower useable bandwidth.

| Solder Type | Liquidous Temp. (degrees C.) | Recommended Platings for Heatsink/Baseplates |
|-------------|------------------------------|--|
| SN63 | 183 eutectic | Nickel, Silver |
| SN96 | 221 eutectic | Nickel, Silver |
| 80Au/20Sn | 280 eutectic | Gold over Nickel |

Figure 2: Proper Mounting Techniques

